

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Zhengyu Zhu	09/25/2010
Yi Li	09/26/2010
FangFang Yang	09/27/2010
RECEIVING PARTY DATA	
Name:	Fairchild Semiconductor Corporation
Street Address:	82 Running Hill Rd.
Internal Address:	MS35-4E
City:	South Portland
State/Country:	MAINE
Postal Code:	04106
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12887821
CORRESPONDENCE DATA	
Fax Number:	(801)321-4893
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>	
Phone:	801-328-3600
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Correspondent Name:	Kenneth E. Horton
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Address Line 4:	Salt Lake City, UTAH 84111
ATTORNEY DOCKET NUMBER:	11948.96
NAME OF SUBMITTER:	Kenneth E. Horton
Total Attachments: 3	

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**PATENT
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ASSIGNMENT

For good and valuable consideration, the receipt of which is hereby acknowledged, the person(s) named below (referred to as "INVENTOR" whether singular or plural) has sold, assigned, and transferred and does hereby sell, assign, and transfer to Fairchild Semiconductor Corporation, 82 Running Hill Rd. MS35-4E, South Portland, ME 04106 ("ASSIGNEE"), for itself and its successors, transferees, and assignees, the following:

1. The entire worldwide right, title, and interest in all inventions and improvements ("SUBJECT MATTER") that are disclosed in the application for United States Letters Patent entitled: High Bond Line Thickness For Semiconductor Devices ("APPLICATION"), which:
 - is to be filed herewith (attorney docket no.)
 - was filed on 9/22/2010 now bearing U.S. Serial No.: 12/887,821 and

2. The entire worldwide right, title, and interest in and to:
 - (a) the APPLICATION, including any right of priority; (b) any divisional, continuation, substitute, renewal, reissue, and other related applications which have been or may be filed in the United States or elsewhere in the world; and (c) any patents which may be granted on the applications set forth in (a) and (b) above.

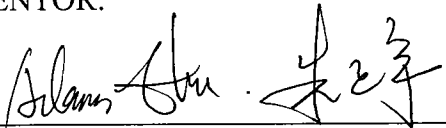
INVENTOR agrees that ASSIGNEE may apply for and receive patents for SUBJECT MATTER in ASSIGNEE's own name.

INVENTOR agrees to do the following, when requested, and without further consideration, in order to carry out the intent of this Assignment: (1) execute all oaths, assignments, powers of attorney, applications, and other papers necessary or desirable to fully secure to ASSIGNEE the rights, titles and interests herein conveyed; (2) communicate to ASSIGNEE all known facts relating to the SUBJECT MATTER; and (3) generally do all lawful acts that ASSIGNEE shall consider desirable for securing, maintaining, and enforcing worldwide patent protection relating to the SUBJECT MATTER and for vesting in ASSIGNEE the rights, titles, and interests herein conveyed. INVENTOR further agrees to provide any successor, assign, or legal representative of ASSIGNEE with the benefits and assistance provided to ASSIGNEE hereunder.

INVENTOR represents that INVENTOR has the right, title, and interests to convey as set forth herein, and covenants with ASSIGNEE that the INVENTOR has made or will make hereafter no assignment, grant, mortgage, license, or other agreement affecting the rights, titles, and interests herein conveyed.

This Assignment may be executed in one or more counterparts, each of which shall be deemed an original and all of which may be taken together as one and the same Assignment.

INVENTOR:



Zhengyu Zhu

Date 2010 - Sep - 25

INVENTOR:

Yi Li

Date _____

INVENTOR:

FangFang Yang


Date _____

INVENTOR:

Zhengyu Zhu

Date _____

INVENTOR:

Yi Li 

Yi Li

Date 2010.09.26

INVENTOR:

FangFang Yang

FangFang Yang

Date 2010.09.27